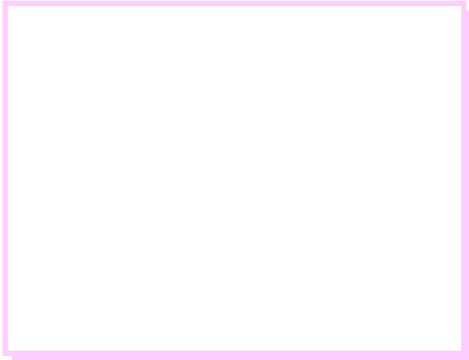


EPA3093

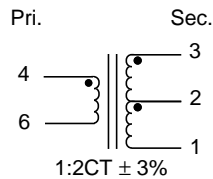


- Robust design withstands soldering processes •
- Complies with or exceeds IEEE Requirements •

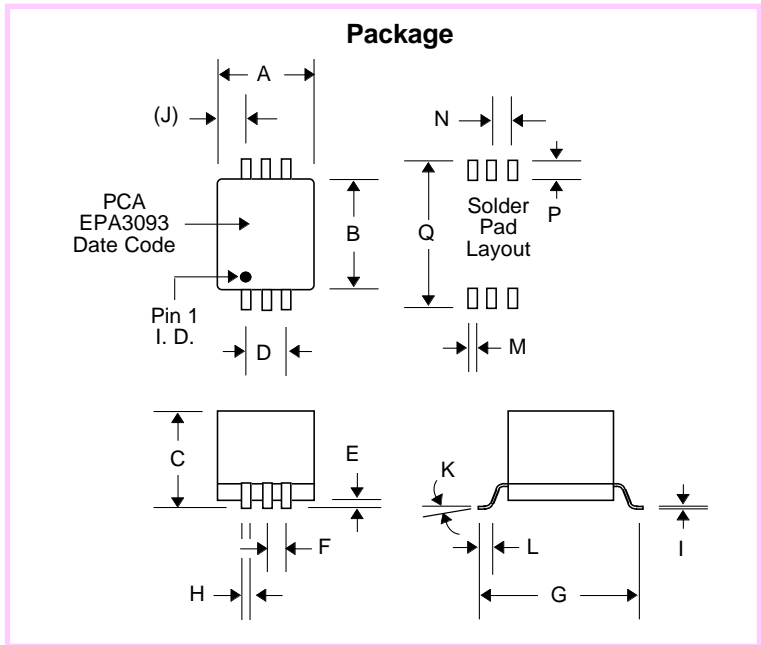
Electrical Parameters @ 25° C

Primary Inductance (μH Min.)	Leakage Inductance (μH Max.)	Hipot (Vrms)	Bandwidth (Ω System)
@ 1 MHz, 20m Vrms (Pins 4-6)	@ 1 MHz, 20m Vrms (Pins 4-6, Pins 3-1 shorted)	Primary to Secondary	.250 - 500 MHz (3 dB Typ.)
19	0.6	1500	75

Schematic



Package



Dimensions

Dim.	(Inches)			(Millimeters)		
	Min.	Max.	Nom.	Min.	Max.	Nom.
A	.280	.300	.290	7.11	7.65	7.36
B	.260	.280	.270	6.60	7.11	6.86
C	.230	.250	.240	5.84	6.35	6.10
D	---	---	.200	---	---	5.08
E	.010	.015	.013	.254	.381	.318
F	---	---	.100	---	---	2.54
G	.380	.400	.390	9.65	10.16	9.91
H	.018	.022	.020	.457	.559	.508
I	.008	.012	.010	.203	.305	.254
(J)	---	---	.060	---	---	1.52
K	0°	8°	---	0°	8°	---
L	.040	.060	.050	1.02	1.52	1.27
M	---	---	.030	---	---	.762
N	---	---	.100	---	---	2.54
P	---	---	.055	---	---	1.40
Q	---	---	.410	---	---	10.41